Silicon P-Channel MOS FET

HITACHI

ADE-208-1193 (Z) 1st. Edition Mar. 2001

Application

Low frequency power amplifier

Complementary pair with 2SK2220, 2SK2221

Features

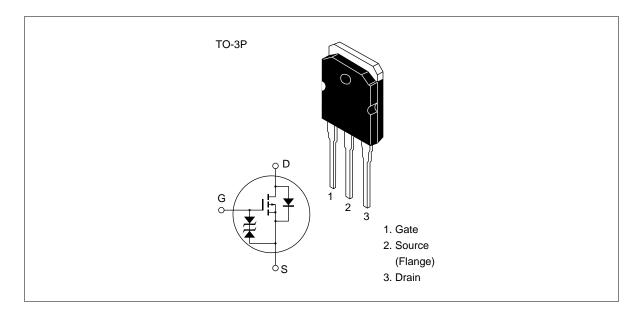
- High power gain
- Excellent frequency response
- High speed switching
- Wide area of safe operation
- Enhancement-mode
- Good complementary characteristics
- Equipped with gate protection diodes

Ordering Information

Type No.	V _{DSX}	
2SJ351	–180 V	_
2SJ352	–200 V	



Outline



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

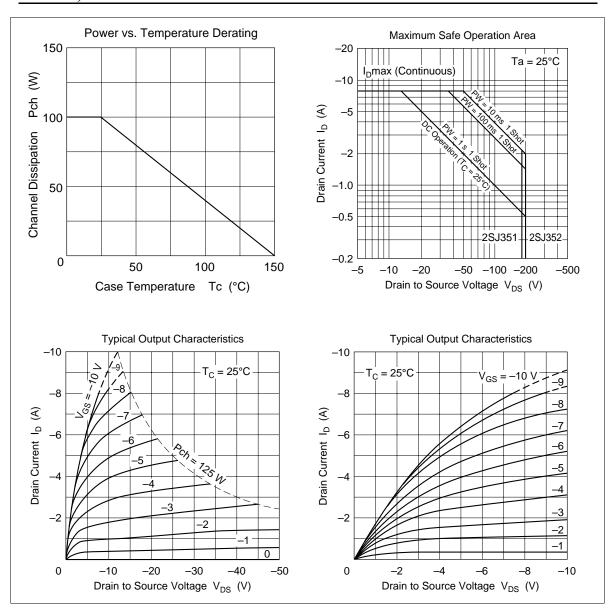
Item		Symbol	Ratings	Unit
Drain to source voltage 2SJ351		$V_{\scriptscriptstyle DSX}$	-180	V
	2SJ352		-200	
Gate to source voltage		$V_{\rm GSS}$	±20	V
Drain current		I _D	-8	Α
Body to drain diode reverse drain current		I _{DR}	-8	A
Channel dissipation		Pch*1	100	W
Channel temperature		Tch	150	°C
Storage temperature		Tstg	-55 to +150	°C

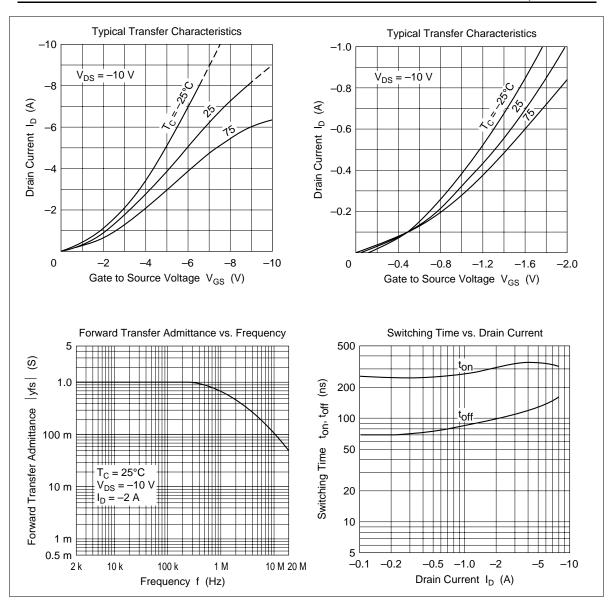
Note: 1. Value at $T_c = 25^{\circ}C$

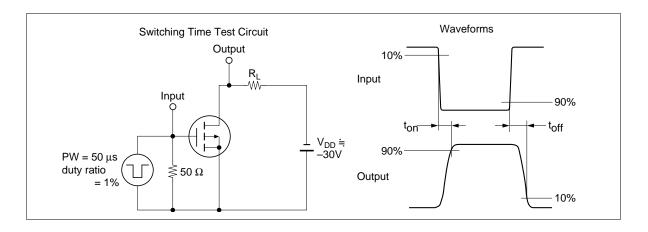
Electrical Characteristics ($Ta = 25^{\circ}C$)

Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SJ351	$V_{(BR)DSX}$	-180	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 10 \text{ V}$
breakdown voltage	2SJ352	_	-200	_	_	_	
Gate to source brea	kdown	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source cutof	f voltage	$V_{GS(off)}$	-0.15	_	-1.45	V	$I_D = -100 \text{ mA}, V_{DS} = -10 \text{ V}$
Drain to source satu voltage	ration	$V_{\text{DS(sat)}}$	_	_	-12	V	$I_D = -8 \text{ A}, V_{GD} = 0^{*1}$
Forward transfer add	mittance	y _{fs}	0.7	1.0	1.4	S	$I_D = -3 \text{ A}, V_{DS} = -10 \text{ V}^{*1}$
Input capacitance		Ciss	_	800	_	pF	$V_{GS} = 5 \text{ V}, V_{DS} = -10 \text{ V},$
Output capacitance		Coss	_	1000	_	pF	f = 1 MHz
Reverse transfer cap	oacitance	Crss	_	18	_	pF	
Turn-on time		t _{on}		320		ns	$V_{DD} = -30 \text{ V}, I_{D} = -4 \text{ A}$
Turn-off time		\mathbf{t}_{off}	_	120	_	ns	

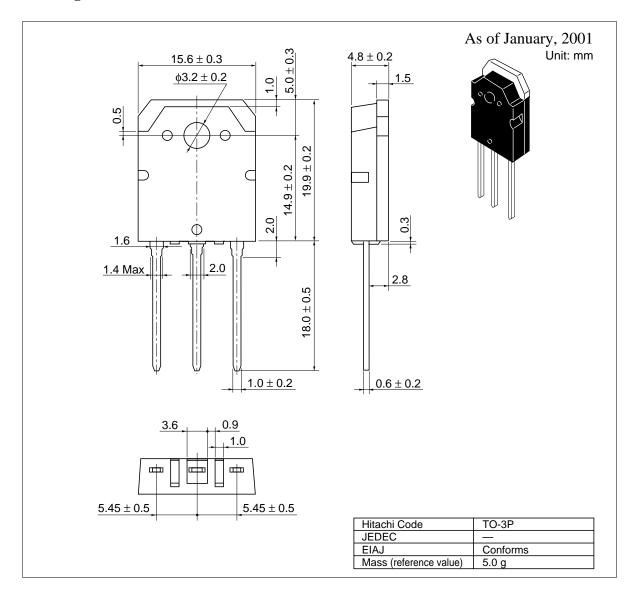
Note: 1. Pulse test







Package Dimensions



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Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL NorthAmerica : http://semiconductor.hitachi.com/ Europe http://www.hitachi-eu.com/hel/ecg Asia http://sicapac.hitachi-asia.com

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Germany

Hitachi Europe GmbH Electronic Components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Fax: <1>(408) 433-0223 Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00

> Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <886>-(2)-2718-3666 Tel: <44> (1628) 585000 Fax: <44> (1628) 585160

Hitachi Asia Ltd. Hitachi Tower 16 Collyer Quay #20-00, Singapore 049318 Tel: <65>-538-6533/538-8577

Fax: <65>-538-6933/538-3877 URL: http://www.hitachi.com.sg Hitachi Asia Ltd

(Taipei Branch Office) 4/F, No. 167, Tun Hwa North Road, Hung-Kuo Building.

Taipei (105), Taiwan Fax: <886>-(2)-2718-8180 Telex: 23222 HAS-TP URL: http://www.hitachi.com.tw Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon, Hong Kong

Tel: <852>-(2)-735-9218 Fax: <852>-(2)-730-0281 URL: http://www.hitachi.com.hk

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